

Features

- Low forward voltage drop
- Low leakage current
- Glass passivated Fast Recovery rectifiers
- Low profile - typical height of 1.0 mm
- Moisture sensitivity: level 1, per J-STD-020
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen-free according to IEC 61249-2-21 definition



Package: eSGP
 (SOD-323F)



RoHS
 COMPLIANT

Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	GSGP 1R	GSGP 2R	GSGP 3R	GSGP 4R	GSGP 5R	GSGP 6R	GSGP 7R	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$						1.0		A
Peak Forward Surge Current 8.3 ms Single Half Sin-wave Superimposed on Rated Load	I_{FSM}						25		A
Operating Junction and Storage Temperature Range	T_J, T_{STG}					- 55 to + 150			°C

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	GSGP 1R	GSGP 2R	GSGP 3R	GSGP 4R	GSGP 5R	GSGP 6R	GSGP 7R	Unit
Maximum Instantaneous Forward Voltage	1 A	V_F				1.3				Volts
Maximum DC Reverse Current	$T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	I_R				5				μA
Typical Reverse Recovery Time	$I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$	t_{rr}			150		250	500		nS
Typical Junction Capacitance	4.0 V, 1 MHz	C_J				5				pF
Typical thermal Resistance ¹⁾	junction to mount	$R_{\theta JM}$				60				°C/W

Note:1) The thermal resistance from junction to mount, mounted on P.C.B with 5x5mm copper pads, 2 OZ, FR4 PCB

Ratings and Characteristics Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

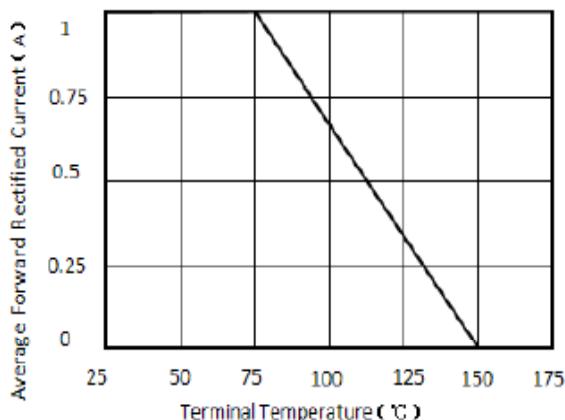


Figure 1. Forward Current Derating Curve

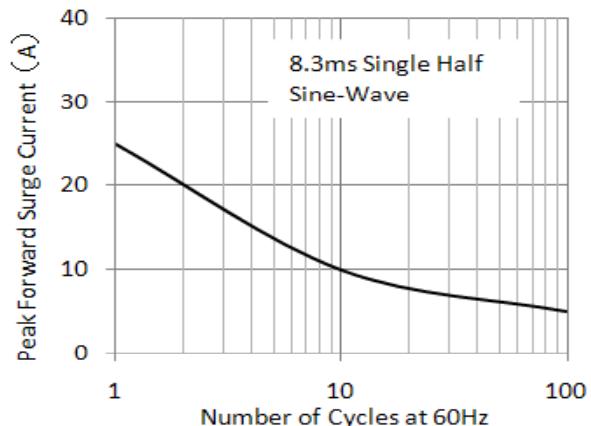


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

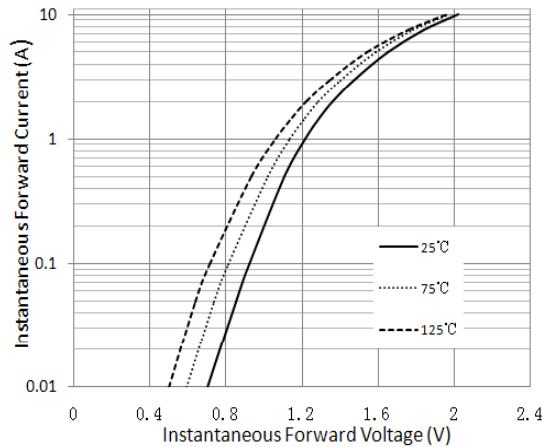


Figure 3. Typical Instantaneous Forward Characteristics

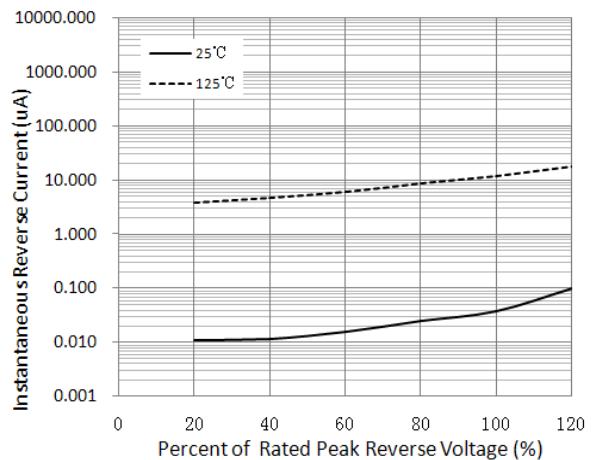


Figure 4. Typical Reverse Characteristics

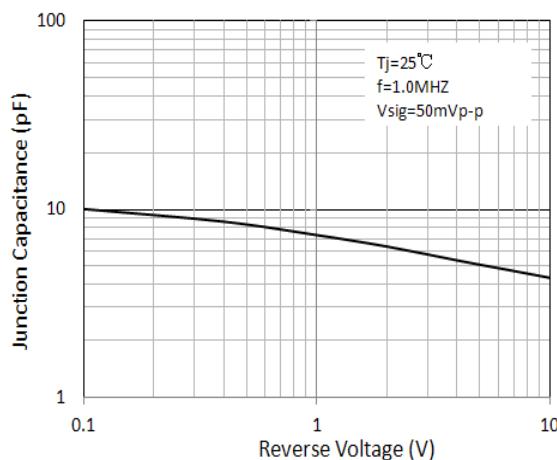
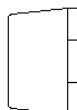
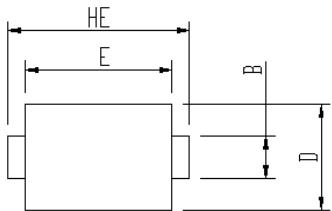


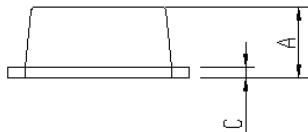
Figure 5. Typical Junction Capacitance

Package Outline Dimensions

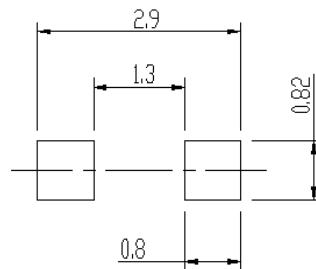
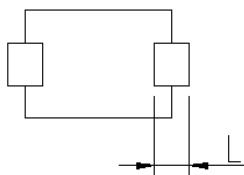
eSGP(SOD-323F)



Package	Unit:mm		Unit:inch	
	MIN	MAX	MIN	MAX
A	0.9	1.08	0.035	0.043
B	0.5	0.7	0.020	0.028
C	0.1	0.25	0.004	0.010
D	1.4	1.6	0.055	0.063
E	2.0	2.2	0.079	0.087
L	0.35	0.65	0.014	0.026
HE	2.4	2.8	0.094	0.110



Soldering footprint



Packing Information

Packing quantities:

3000 pcs/Reel, 40 Reels/Box; 8mm Tape, 7" Reel

Tape & Reel Specification

